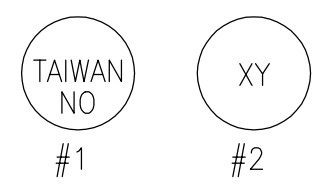


BOTTOM E-PIN INDENT #2 ø2.80  
NOTE 6

DETAIL "A"

- NOTE :
1. CONTROLLING DIMENSION : mm
  2. LEAD FRAME MATERIAL : COPPER C7025
  3. AFTER SOLDER PLATING LEAD THICKNESS WILL BE 0.20mm MAX.
  4. TOLERANCE ON THE POSITION OF THE LEADS IS 0.120mm MAXIMUM
  5. PACKAGE BODY DIMENSIONS D1 AND E1 DO NOT INCLUDE THE MOLD PROTRUSION MAXIMUM MOLD PROTRUSION IS 0.25mm.
  6. BOTTOM E-PIN INDENT ARE MARKED AS BELOW :



X : A ~ M  
Y : 1 ~ 6  
NO : DENOTE MOLD SET NUMBER

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	—	—	3.40	—	—	0.134
A1	0.05	—	0.50	0.002	—	0.020
A2	2.57	2.79	2.87	0.101	0.110	0.113
b	0.23	—	0.38	0.009	—	0.015
C	0.10	0.15	0.20	0.004	0.006	0.008
E	17.65	17.90	18.15	0.695	0.705	0.715
E1	13.90	14.00	14.10	0.547	0.551	0.555
D	23.65	23.90	24.15	0.931	0.941	0.951
D1	19.90	20.00	20.10	0.783	0.787	0.791
e	—	0.65	—	—	0.0256	—
L	0.65	0.80	0.95	0.0256	0.0315	0.037
L1	—	1.95	—	—	0.077	—
θ	0°	—	7°	0°	—	7°
y	0.00	—	0.076	0.000	—	0.003

CUSTOMER :		LINGSEN 5-1 NAN 2ND ROAD T.E.P.Z PRECISION IND, LTD TAICHUNG, TAIWAN. R. O. C	
APPROVED BY	DATE	TITLE : 100L QFP PACKAGE OUTLINE DRAWING (14x20 mm) FOOTPRINT: 3.9mm	
DRAW BY: <i>Vicky Chen</i>	01/04/'99		
CHECK BY: <i>Thomas Kao</i>	01/05/'99		
APPROVAL: <i>Paul Leu</i>	01/06/'99	DWG. NO. PO-QFP-004	REV. 0
APPROVAL: <i>Barry Chen</i>	01/06/'99	UNIT : mm	SCALE : 4/1
		SHEET 1 OF 1	